

SGM8634 470µA, 6MHz, Rail-to-Rail I/O CMOS Operational Amplifier

PRODUCT DESCRIPTION

The quad SGM8634 is a low noise, low voltage, and low power operational amplifier that can be designed into a wide range of applications. The SGM8634 has a high gain-bandwidth product of 6MHz, a slew rate of $3.7V/\mu s$, and a quiescent current of $470\mu A/amplifier$ at 5V.

The SGM8634 is designed to provide optimal performance in low voltage and low noise systems. It provides rail-to-rail output swing into heavy loads. The input common mode voltage range includes ground, and the maximum input offset voltage is 3.5mV. The operating range is from 2.5V to 5.5V.

The quad SGM8634 is available in Green TSSOP-14 and SOIC-14 packages. It is specified over the extended industrial temperature range (-40°C to +125°C).

FEATURES

- Rail-to-Rail Input and Output
 0.8mV Typical Vos
- High Gain-Bandwidth Product: 6MHz
- High Slew Rate: 3.7V/µs
- Settling Time to 0.1% with 2V Step: 2.1µs
- Overload Recovery Time: 0.9µs
- Low Noise: $12nV/\sqrt{Hz}$
- Supply Voltage Range: 2.5V to 5.5V
- Input Voltage Range: -0.1V to +5.6V with V_s = 5.5V
- Low Supply Current 470µA/Amplifier (TYP)
- Available in Green TSSOP-14 and SOIC-14 Packages

APPLICATIONS

- Sensors Audio Active Filters A/D Converters Communications Test Equipment Cellular and Cordless Phones Laptops and PDAs Photodiode Amplification
- Battery-Powered Instrumentation



PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM8634	TSSOP-14	-40°C to +125°C	SGM8634XTS14/TR	SGM8634 XTS14 XXXXX	Tape and Reel, 3000
	SOIC-14	-40°C to +125°C	SGM8634XS14/TR	SGM8634XS14 XXXXX	Tape and Reel, 2500

NOTE: XXXXX = Date Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, +V _S to -V _S	V
$(-V_s) - 0.3V$ to $(+V_s) + 0.3V$	V
Storage Temperature Range65°C to +150°C	
Junction Temperature	С
Operating Temperature Range40°C to +125°C	С
Lead Temperature (Soldering 10sec)	С
ESD Susceptibility	
HBM1500\	V
MM400	V

OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

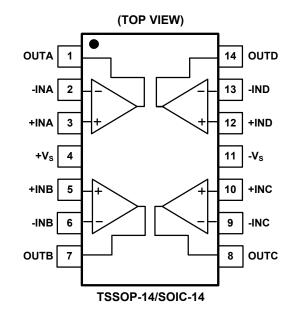
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.

PIN CONFIGURATION

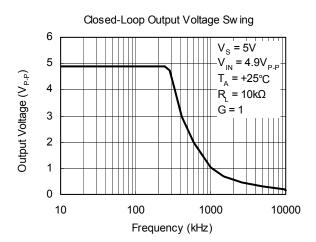


ELECTRICAL CHARACTERISTICS

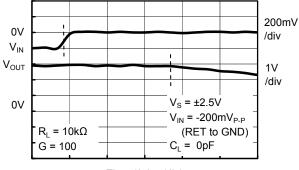
(At T_A = +25°C, V_S = 5V, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.)

		SGM8634							
		ТҮР	MIN/MAX OVER TEMPERATURE						
PARAMETER	CONDITIONS	+25℃	+25℃	0℃ to 70℃	-40℃ to 85℃	-40℃ to 125℃	UNITS	Min/ Max	
INPUT CHARACTERISTICS			-						
Input Offset Voltage (Vos)		0.8	3.5	3.9	4.3	4.6	mV	MAX	
Input Bias Current (I _B)		1					pА	TYP	
Input Offset Current (I _{OS})		1					pА	TYP	
Input Common Mode Voltage Range (V_{CM})	V _S = 5.5V	-0.1 to +5.6					V	TYP	
Common Mode Rejection Ratio (CMRR)	$V_{\rm S}$ = 5.5V, $V_{\rm CM}$ = -0.1V to 4V	90	73	70	70	65	dB	MIN	
	$V_{\rm S}$ = 5.5V, $V_{\rm CM}$ = -0.1V to 5.6V	83					dB	MIN	
Open-Loop Voltage Gain (A _{OL})	$R_{\rm L}$ = 600 $\Omega, V_{\rm O}$ = 0.15 V to 4.85 V	97	90	87	86	79	dB	MIN	
	R_L = 10k Ω , V_O = 0.05V to 4.95V	108					dB	MIN	
Input Offset Voltage Drift ($\Delta V_{OS}/\Delta_T$)		2.4					µV/℃	TYP	
OUTPUT CHARACTERISTICS		1	•	1					
Output Voltage Swing from Rail	R _L = 600Ω	0.1					V	TYP	
	R _L = 10kΩ	0.015					V	TYP	
Output Current (I _{OUT})	nt (I _{OUT})		49	45	40	35	mA	MIN	
Closed-Loop Output Impedance f = 200kHz, G = 1		3					Ω	TYP	
POWER SUPPLY				-					
Operating Voltage Range			2.5	2.5	2.5	2.5	V	MIN	
			5.5	5.5	5.5	5.5	V	MAX	
Power Supply Rejection Ratio (PSRR)	V _s = 2.5V to 5.5V								
	V_{CM} = (- V_{S}) + 0.5V	91	74	72	72	68	dB	MIN	
Quiescent Current/Amplifier (I _Q)	I _{OUT} = 0	470	650	727	750	815	μA	MAX	
DYNAMIC PERFORMANCE		1	n	1					
Gain-Bandwidth Product (GBP)	$R_L = 10k\Omega$	6					MHz	TYP	
Phase Margin (ϕ_{O})		60					degrees	TYP	
Full Power Bandwidth (BW _P)	< 1% distortion, R_L = 600 Ω	250					kHz	TYP	
Slew Rate (SR)	G = +1, 2V Step, R _L = 10kΩ	3.7					V/µs	TYP	
Settling Time to 0.1% (t _s)	G = +1, 2V Step, R _L = 600Ω	2.1					μs	TYP	
Overload Recovery Time V_{IN} Gain = V_{S} , R_L = 600 Ω		0.9					μs	TYP	
NOISE PERFORMANCE	•	•		•		-			
Voltage Noise Density (e _n)	f = 1kHz	12					nV/ _{√Hz}	TYP	
Current Noise Density (i _n)	f = 1kHz	3					fA/ √ _{Hz}	TYP	

At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.

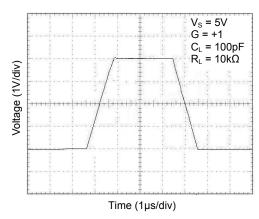


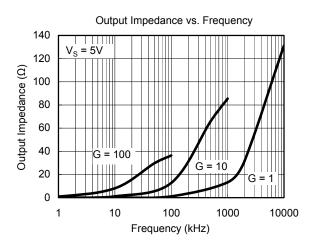




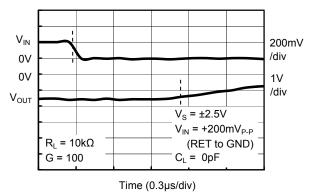
Time (0.3µs/div)

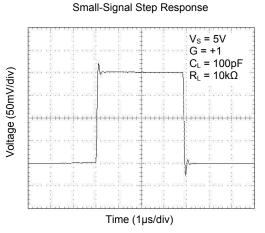






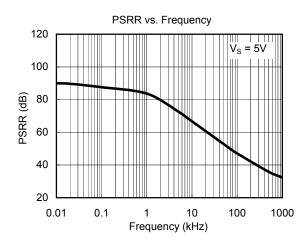


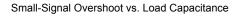


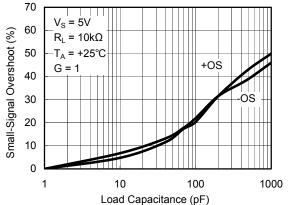


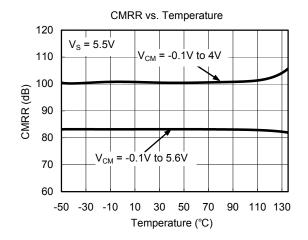
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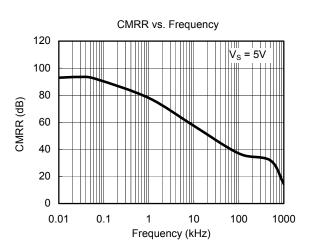
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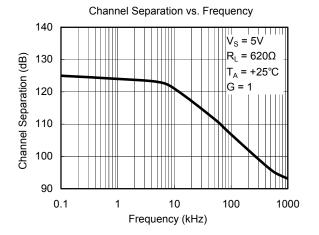


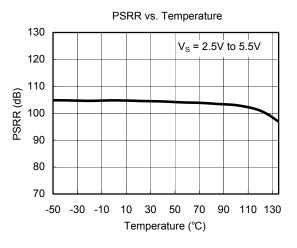






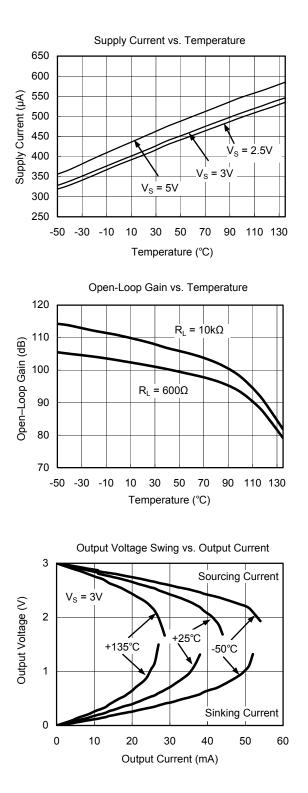


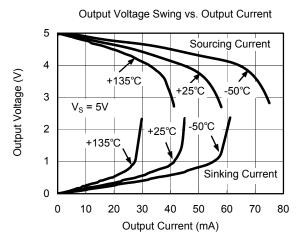


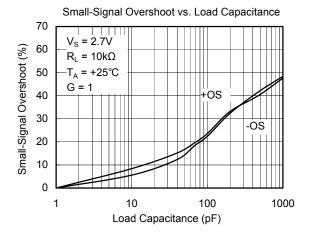


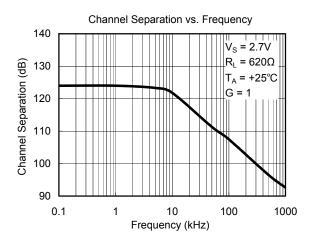
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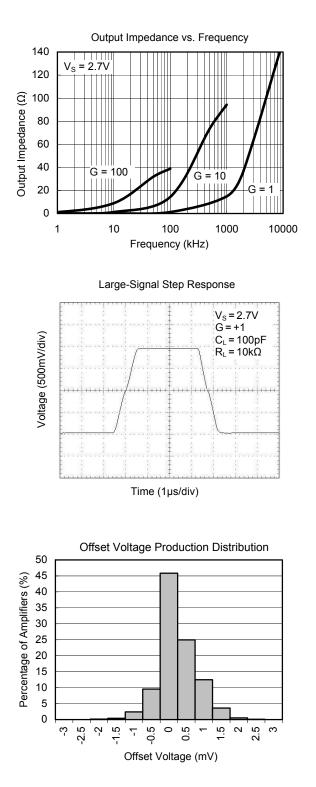


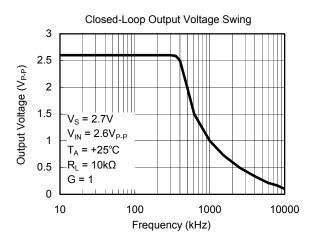


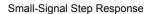


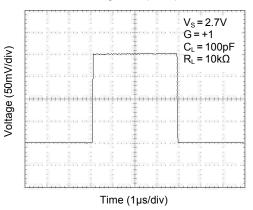
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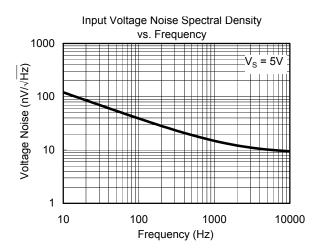
At T_A = +25°C, V_{CM} = $V_S/2$, R_L = 600 Ω , unless otherwise noted.











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APPLICATION NOTES

Driving Capacitive Loads

The SGM8634 can directly drive 1000pF in unity-gain without oscillation. The unity-gain follower (buffer) is the most sensitive configuration to capacitive loading. Direct capacitive loading reduces the phase margin of the amplifier and this results in ringing or even oscillation. Applications that require greater capacitive driving capability should use an isolation resistor between the output and the capacitive load like the circuit in Figure 1. The isolation resistor R_{ISO} and the load capacitor C_L form a zero to increase stability. The bigger the R_{ISO} resistor value, the more stable V_{OUT} will be. Note that this method results in a loss of gain accuracy because R_{ISO} forms a voltage divider with the R_{LOAD}.

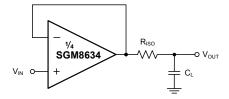


Figure 1. Indirectly Driving Heavy Capacitive Load

An improved circuit is shown in Figure 2. It provides DC accuracy as well as AC stability. R_F provides the DC accuracy by connecting the inverting signal with the output. C_F and R_{iso} serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving phase margin in the overall feedback loop.

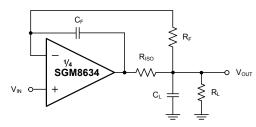


Figure 2. Indirectly Driving Heavy Capacitive Load with DC Accuracy

For non-buffer configuration, there are two other ways to increase the phase margin: (a) by increasing the amplifier's closed-loop gain or (b) by placing a capacitor in parallel with the feedback resistor to counteract the parasitic capacitance associated with inverting node.

Power-Supply Bypassing and Layout

The SGM8634 operates from either a single +2.5V to +5.5V supply or dual $\pm 1.25V$ to $\pm 2.75V$ supplies. For single-supply operation, bypass the power supply +V_s with a 0.1µF ceramic capacitor which should be placed close to the +V_s pin. For dual-supply operation, both the +V_s and the -V_s supplies should be bypassed to ground with separate 0.1µF ceramic capacitors. 2.2µF tantalum capacitor can be added for better performance.

Good PC board layout techniques optimize performance by decreasing the amount of stray capacitance at the op amp's inputs and output. To decrease stray capacitance, minimize trace lengths and widths by placing external components as close to the device as possible. Use surface-mount components whenever possible.

For the operational amplifier, soldering the part to the board directly is strongly recommended. Try to keep the high frequency current loop area small to minimize the EMI (electromagnetic interfacing).

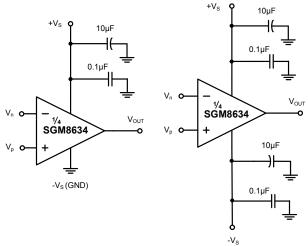


Figure 3. Amplifier with Bypass Capacitors

Grounding

A ground plane layer is important for SGM8634 circuit design. The length of the current path in an inductive ground return will create an unwanted voltage noise. Broad ground plane areas will reduce the parasitic inductance.

Input-to-Output Coupling

To minimize capacitive coupling, the input and output signal traces should not be in parallel. This helps reduce unwanted positive feedback.



TYPICAL APPLICATION CIRCUITS

Differential Amplifier

The circuit shown in Figure 4 performs the difference function. If the resistor ratios are equal $(R_4/R_3 = R_2/R_1)$, then $V_{OUT} = (V_p - V_n) \times R_2/R_1 + V_{REF}$.

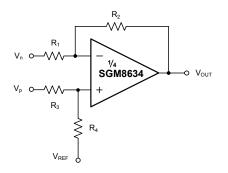


Figure 4. Differential Amplifier

Instrumentation Amplifier

The circuit in Figure 5 performs the same function as that in Figure 4 but with a high input impedance.

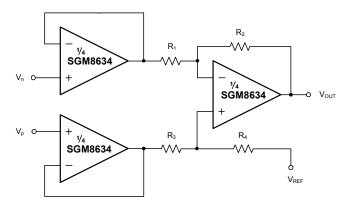


Figure 5. Instrumentation Amplifier

Low-Pass Active Filter

The low-pass filter shown in Figure 6 has a DC gain of $(-R_2/R_1)$ and the -3dB corner frequency is $1/2\pi R_2 C$. Make sure the filter bandwidth is within the bandwidth of the amplifier. The large values of feedback resistors can couple with parasitic capacitance and cause undesired effects such as ringing or oscillation in high-speed amplifiers. Keep resistor values as low as possible and consistent with output loading consideration.

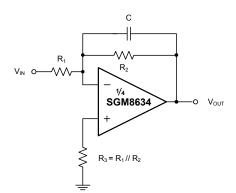
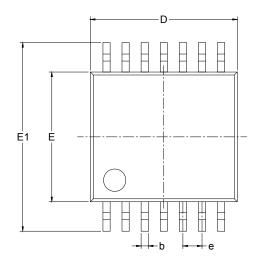
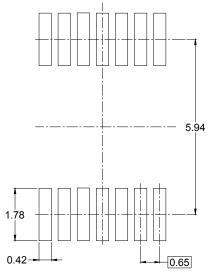


Figure 6. Low-Pass Active Filter

PACKAGE OUTLINE DIMENSIONS

TSSOP-14





RECOMMENDED LAND PATTERN (Unit: mm)



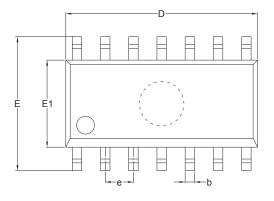


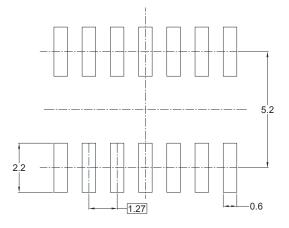
Symbol		nsions meters	Dimensions In Inches			
	MIN	MAX	MIN	MAX		
A		1.200		0.047		
A1	0.050	0.150	0.002	0.006		
A2	0.800	1.050	0.031	0.041		
b	0.190	0.300	0.007	0.012		
С	0.090	0.200	0.004	0.008		
D	4.860	5.100	0.191	0.201		
E	4.300	4.500	0.169	0.177		
E1	6.250	6.550	0.246	0.258		
e	0.650	BSC	0.026	BSC		
L	0.500	0.700	0.02	0.028		
Н	0.25 TYP		0.01	TYP		
θ	1° 7°		1°	7°		



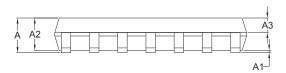
PACKAGE OUTLINE DIMENSIONS

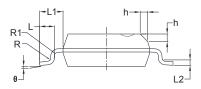
SOIC-14





RECOMMENDED LAND PATTERN (Unit: mm)



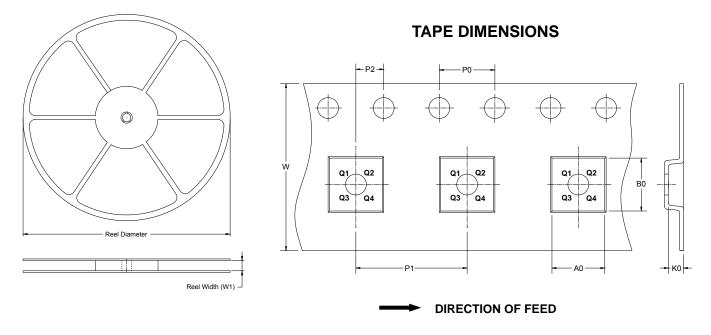


Symbol		nsions imeters	Dimensions In Inches			
	MIN	MAX	MIN	MAX		
А	1.35	1.75	0.053	0.069		
A1	0.10	0.25	0.004	0.010		
A2	1.25	1.65	0.049	0.065		
A3	0.55	0.75	0.022	0.030		
b	0.36	0.49	0.014	0.019		
D	8.53	8.73	0.336	0.344		
E	5.80	6.20	0.228	0.244		
E1	3.80	4.00	0.150	0.157		
е	1.27	'BSC	0.050 BSC			
L	0.45	0.80	0.018	0.032		
L1	1.04	REF	0.040 REF			
L2	0.25	5 BSC	0.01 BSC			
R	0.07		0.003			
R1	0.07		0.003			
h	0.30	0.50	0.012	0.020		
θ	0° 8°		0°	8°		



TAPE AND REEL INFORMATION

REEL DIMENSIONS



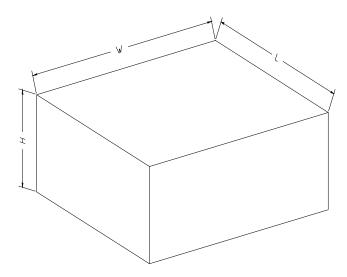
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KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-14	13″	12.4	6.95	5.6	1.2	4.0	8.0	2.0	12.0	Q1
SOIC-14	13″	16.4	6.6	9.3	2.1	4.0	8.0	2.0	16.0	Q1



CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length Width (mm) (mm)		Height (mm)	Pizza/Carton	
13″	386	280	370	5	DD0002

